

Hex Contact Bounce Eliminator

MC14490

The MC14490 is constructed with complementary MOS enhancement mode devices, and is used for the elimination of extraneous level changes that result when interfacing with mechanical contacts. The digital contact bounce eliminator circuit takes an input signal from a bouncing contact and generates a clean digital signal four clock periods after the input has stabilized. The bounce eliminator circuit will remove bounce on both the “make” and the “break” of a contact closure. The clock for operation of the MC14490 is derived from an internal R-C oscillator which requires only an external capacitor to adjust for the desired operating frequency (bounce delay). The clock may also be driven from an external clock source or the oscillator of another MC14490 (see Figure 5).

NOTE: Immediately after powerup, the outputs of the MC14490 are in indeterminate states.

Features

- Diode Protection on All Inputs
- Six Debouncers Per Package
- Internal Pullups on All Data Inputs
- Can Be Used as a Digital Integrator, System Synchronizer, or Delay Line
- Internal Oscillator (R-C), or External Clock Source
- TTL Compatible Data Inputs/Outputs
- Single Line Input, Debounces Both “Make” and “Break” Contacts
- Does Not Require “Form C” (Single Pole Double Throw) Input Signal
- Cascadable for Longer Time Delays
- Schmitt Trigger on Clock Input (Pin 7)
- Supply Voltage Range = 3.0 V to 18 V
- Chip Complexity: 546 FETs or 136.5 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in}, V_{out}	-0.5 to V_{DD} + 0.5	V
Input Current (DC or Transient) per Pin	I_{in}	±10	mA
Power Dissipation, per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	-55 to +125	°C
Storage Temperature Range	T_{stg}	-65 to +150	°C
Lead Temperature (8-Second Soldering)	T_L	260	°C

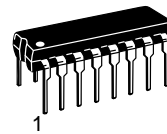
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: Plastic “P and D/DW” Packages: -7.0 mW/°C From 65 °C To 125 °C

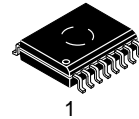
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

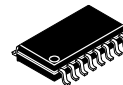
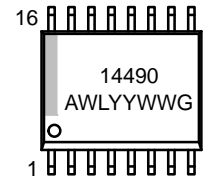
MARKING DIAGRAMS



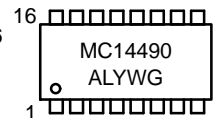
PDIP-16
P SUFFIX
CASE 648



SOIC-16
DW SUFFIX
CASE 751G



SOEIAJ-16
F SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

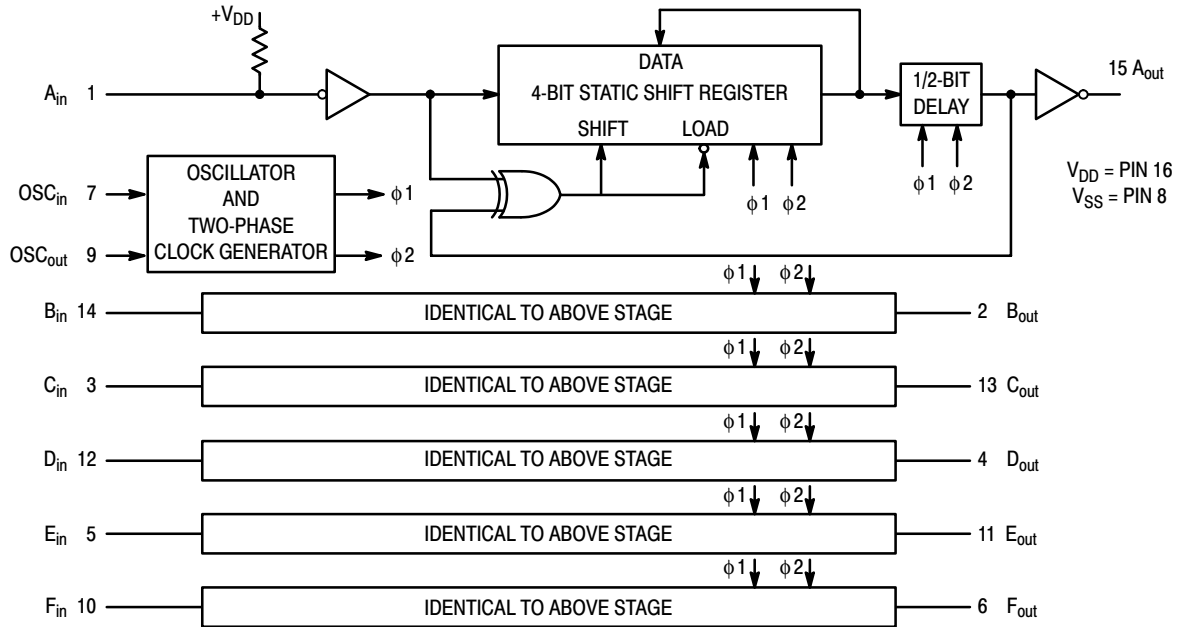
NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 9.

MC14490

PIN ASSIGNMENT

A_{in}	1	16	V_{DD}
B_{out}	2	15	A_{out}
C_{in}	3	14	B_{in}
D_{out}	4	13	C_{out}
E_{in}	5	12	D_{in}
F_{out}	6	11	E_{out}
OSC_{in}	7	10	F_{in}
V_{SS}	8	9	OSC_{out}

BLOCK DIAGRAM



MC14490

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	– 55 °C		25 °C			125 °C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage “0” Level V _{in} = V _{DD} or 0	V _{OL}	5.0	–	0.05	–	0	0.05	–	0.05	Vdc
		10	–	0.05	–	0	0.05	–	0.05	
		15	–	0.05	–	0	0.05	–	0.05	
	V _{OH}	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
“1” Level V _{in} = 0 or V _{DD}	V _{OH}	10	9.95	–	9.95	10	–	9.95	–	Vdc
		15	14.95	–	14.95	15	–	14.95	–	
		15	14.95	–	14.95	15	–	14.95	–	
	V _{IL}	5.0	–	1.5	–	2.25	1.5	–	1.5	Vdc
Input Voltage “0” Level (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	10	–	3.0	–	4.50	3.0	–	3.0	Vdc
		15	–	4.0	–	6.75	4.0	–	4.0	
		15	–	4.0	–	6.75	4.0	–	4.0	
	V _{IH}	5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc
(V _O = 0.5 or 4.5 Vdc) “1” Level (V _O = 1.0 or 9.0 Vdc) (V _O = 1.5 or 13.5 Vdc)	V _{IH}	10	7.0	–	7.0	5.50	–	7.0	–	Vdc
		15	11	–	11	8.25	–	11	–	
		15	11	–	11	8.25	–	11	–	
	V _{IH}	5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc
Output Drive Current Oscillator Output (V _{OH} = 2.5 V) (V _{OH} = 4.6 V) (V _{OH} = 9.5 V) (V _{OH} = 13.5 V)	I _{OH}	5.0	– 0.6	–	– 0.5	– 1.5	–	– 0.4	–	mAdc
		5.0	– 0.12	–	– 0.1	– 0.3	–	– 0.08	–	
		10	– 0.23	–	– 0.2	– 0.8	–	– 0.16	–	
		15	– 1.4	–	– 1.2	– 3.0	–	– 1.0	–	
Debounce Outputs (V _{OH} = 2.5 V) (V _{OH} = 4.6 V) (V _{OH} = 9.5 V) (V _{OH} = 13.5 V)	I _{OH}	5.0	– 0.9	–	– 0.75	– 2.2	–	– 0.6	–	mAdc
		5.0	– 0.19	–	– 0.16	– 0.46	–	– 0.12	–	
		10	– 0.6	–	– 0.5	– 1.2	–	– 0.4	–	
		15	1.8	–	– 1.5	– 4.5	–	– 1.2	–	
Oscillator Output (V _{OL} = 0.4 V) (V _{OL} = 0.5 V) (V _{OL} = 1.5 V)	I _{OL}	5.0	0.36	–	0.3	0.9	–	0.24	–	mAdc
		10	0.9	–	0.75	2.3	–	0.6	–	
		15	4.2	–	3.5	10	–	2.8	–	
	I _{OL}	5.0	2.6	–	2.2	4.0	–	1.8	–	mAdc
Debounce Outputs (V _{OL} = 0.4 V) (V _{OL} = 0.5 V) (V _{OL} = 1.5 V)	I _{OL}	10	4.0	–	3.3	9.0	–	2.7	–	mAdc
		15	12	–	10	35	–	8.1	–	
		15	12	–	10	35	–	8.1	–	
	I _{OL}	5.0	2.6	–	2.2	4.0	–	1.8	–	mAdc
Input Current Debounce Inputs (V _{in} = V _{DD})	I _{IH}	15	–	2.0	–	0.2	2.0	–	11	μAdc
Input Current Oscillator — Pin 7 (V _{in} = V _{SS} or V _{DD})	I _{in}	15	–	± 620	–	± 255	± 400	–	± 250	μAdc
Pullup Resistor Source Current Debounce Inputs (V _{in} = V _{SS})	I _{IL}	5.0	210	425	140	190	255	70	225	μAdc
	I _{IL}	10	400	840	280	380	500	145	440	μAdc
		15	600	1250	415	570	750	215	660	
Input Capacitance	C _{in}	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (V _{in} = V _{SS} or V _{DD} , I _{out} = 0 μA)	I _{SS}	5.0	–	150	–	40	100	–	90	μAdc
		10	–	280	–	90	225	–	180	
		15	–	840	–	225	650	–	550	

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

MC14490

SWITCHING CHARACTERISTICS (Note 3) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ \text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 4)	Max	Unit
Output Rise Time All Outputs	t_{TLH}	5.0 10 15	— — —	180 90 65	360 180 130	ns
Output Fall Time Oscillator Output	t_{THL}	5.0 10 15	— — —	100 50 40	200 100 80	ns
Debounce Outputs	t_{THL}	5.0 10 15	— — —	60 30 20	120 60 40	ns
Propagation Delay Time Oscillator Input to Debounce Outputs	t_{PHL}	5.0 10 15	— — —	285 120 95	570 240 190	ns
	t_{PLH}	5.0 10 15	— — —	370 160 120	740 320 240	ns
Clock Frequency (50% Duty Cycle) (External Clock)	f_{cl}	5.0 10 15	— — —	2.8 6 9	1.4 3.0 4.5	MHz
Setup Time (See Figure 1)	t_{su}	5.0 10 15	100 80 60	50 40 30	— — —	ns
Maximum External Clock Input Rise and Fall Time Oscillator Input	t_r, t_f	5.0 10 15	No Limit			ns
Oscillator Frequency OSC_{out} $C_{ext} \geq 100 \text{ pF}$ Note: These equations are intended to be a design guide. Laboratory experimentation may be required. Formulas are typically $\pm 15\%$ of actual frequencies.	$f_{osc, typ}$	5.0 10 15	$\frac{1.5}{C_{ext} \text{ (in } \mu\text{F)}}$ $\frac{4.5}{C_{ext} \text{ (in } \mu\text{F)}}$ $\frac{6.5}{C_{ext} \text{ (in } \mu\text{F)}}$			Hz

3. The formulas given are for the typical characteristics only at 25°C .

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

*POWER-DOWN CONSIDERATIONS

Large values of C_{ext} may cause problems when powering down the MC14490 because of the amount of energy stored in the capacitor. When a system containing this device is powered down, the capacitor may discharge through the input protection diodes at Pin 7 or the parasitic diodes at Pin 9. Current through these internal diodes must be limited to 10 mA, therefore the turn-off time of the power supply must not be faster than $t = (V_{DD} - V_{SS}) \cdot C_{ext} / (10 \text{ mA})$. For example, If $V_{DD} - V_{SS} = 15 \text{ V}$ and $C_{ext} = 1 \mu\text{F}$, the power supply must turn off no faster than $t = (15 \text{ V}) \cdot (1 \mu\text{F}) / 10 \text{ mA} = 1.5 \text{ ms}$. This is usually not a problem because power supplies are heavily filtered and cannot discharge at this rate.

When a more rapid decrease of the power supply to zero volts occurs, the MC14490 may sustain damage. To avoid this possibility, use external clamping diodes, D1 and D2, connected as shown in Figure 2.

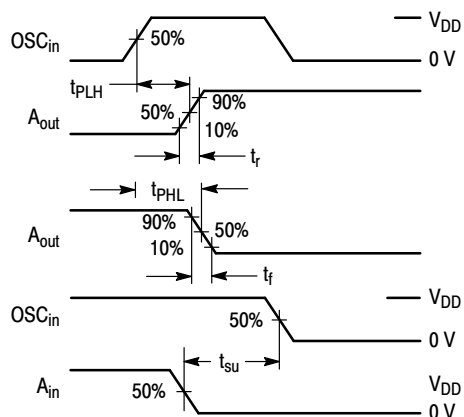


Figure 1. Switching Waveforms

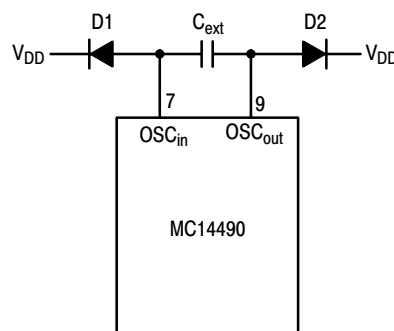


Figure 2. Discharge Protection During Power Down

THEORY OF OPERATION

The MC14490 Hex Contact Bounce Eliminator is basically a digital integrator. The circuit can integrate both up and down. This enables the circuit to eliminate bounce on both the leading and trailing edges of the signal, shown in the timing diagram of Figure 3.

Each of the six Bounce Eliminators is composed of a 4-1/2-bit register (the integrator) and logic to compare the input with the contents of the shift register, as shown in Figure 4. The shift register requires a series of timing pulses in order to shift the input signal into each shift register location. These timing pulses (the clock signal) are represented in the upper waveform of Figure 3. Each of the six Bounce Eliminator circuits has an internal resistor as shown in Figure 4. A pullup resistor was incorporated rather than a pulldown resistor in order to implement switched ground input signals, such as those coming from relay contacts and push buttons. By switching ground, rather than a power supply lead, system faults (such as shorts to ground on the signal input leads) will not cause excessive currents in the wiring and contacts. Signal lead shorts to ground are much more probable than shorts to a power supply lead.

When the relay contact is closed, (see Figure 4) the low level is inverted, and the shift register is loaded with a high on each positive edge of the clock signal. To understand the operation, we assume all bits of the shift register are loaded with lows and the output is at a high level.

At clock edge 1 (Figure 3) the input has gone low and a high has been loaded into the first bit or storage location of the shift register. Just after the positive edge of clock 1, the input signal has bounced back to a high. This causes the shift register to be reset to lows in all four bits — thus starting the timing sequence over again.

During clock edges 3 to 6 the input signal has stayed low. Thus, a high has been shifted into all four shift register bits and, as shown, the output goes low during the positive edge of clock pulse 6.

It should be noted that there is a 3-1/2 to 4-1/2 clock period delay between the clean input signal and output signal. In this example there is a delay of 3.8 clock periods from the beginning of the clean input signal.

After some time period of N clock periods, the contact is opened and at N+1 a low is loaded into the first bit. Just after N+1, when the input bounces low, all bits are set to a high. At N+2 nothing happens because the input and output are low and all bits of the shift register are high. At time N+3 and thereafter the input signal is a high, clean signal. At the positive edge of N+6 the output goes high as a result of four lows being shifted into the shift register.

Assuming the input signal is long enough to be clocked through the Bounce Eliminator, the output signal will be no longer or shorter than the clean input signal plus or minus one clock period.

The amount of time distortion between the input and output signals is a function of the difference in bounce characteristics on the edges of the input signal and the clock frequency. Since most relay contacts have more bounce when making as compared to breaking, the overall delay, counting bounce period, will be greater on the leading edge of the input signal than on the trailing edge. Thus, the output signal will be shorter than the input signal — if the leading edge bounce is included in the overall timing calculation.

The only requirement on the clock frequency in order to obtain a bounce free output signal is that four clock periods do not occur while the input signal is in a false state. Referring to Figure 3, a false state is seen to occur three times at the beginning of the input signal. The input signal goes low three times before it finally settles down to a valid low state. The first three low pulses are referred to as false states.

If the user has an available clock signal of the proper frequency, it may be used by connecting it to the oscillator input (pin 7). However, if an external clock is not available the user can place a small capacitor across the oscillator input and output pins in order to start up an internal clock source (as shown in Figure 4). The clock signal at the oscillator output pin may then be used to clock other MC14490 Bounce Eliminator packages. With the use of the MC14490, a large number of signals can be cleaned up, with the requirement of only one small capacitor external to the Hex Bounce Eliminator packages.

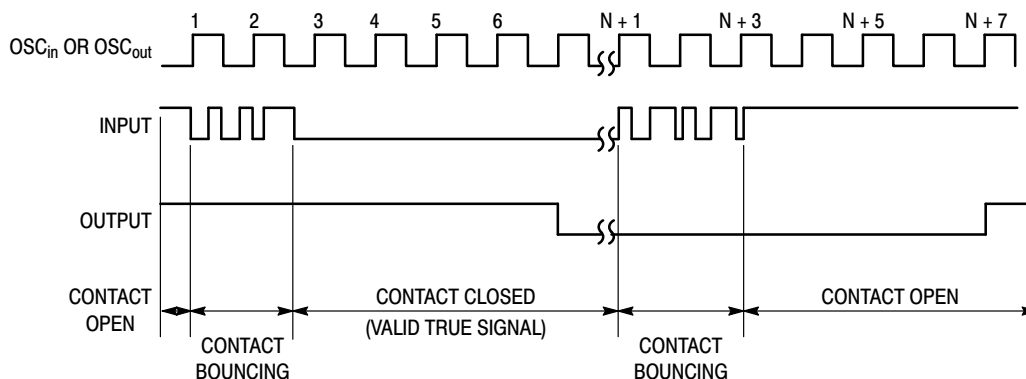
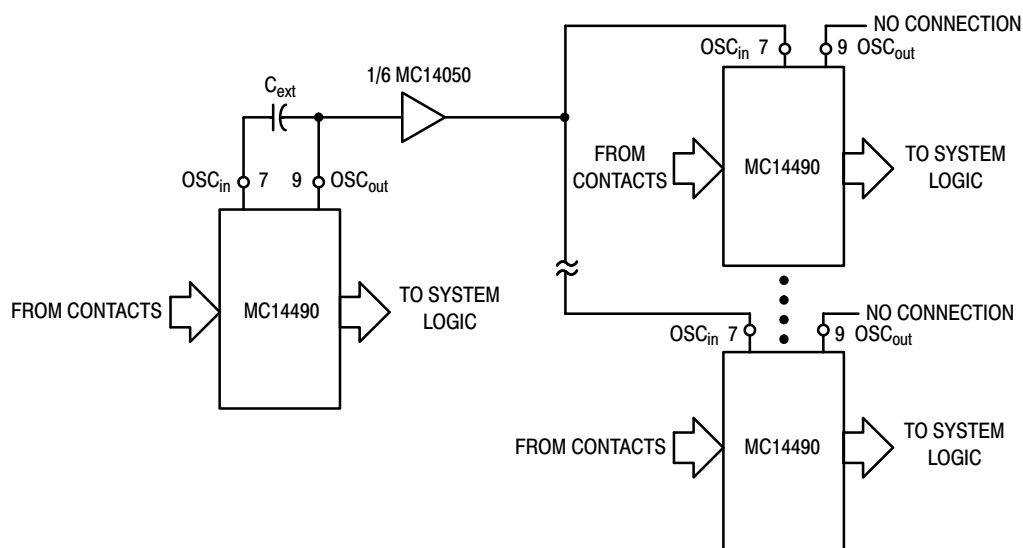


Figure 3. Timing Diagram



TYPICAL APPLICATIONS

ASYMMETRICAL TIMING

In applications where different leading and trailing edge delays are required (such as a fast attack/slow release timer.) Clocks of different frequencies can be gated into the MC14490 as shown in Figure 6. In order to produce a slow attack/fast release circuit leads A and B should be interchanged. The clock out lead can then be used to feed clock signals to the other MC14490 packages where the asymmetrical input/output timing is required.

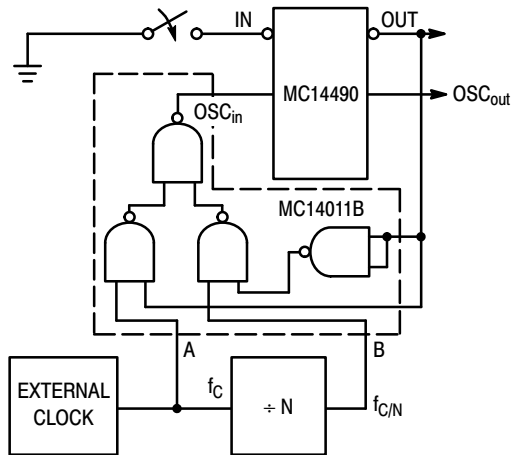


Figure 6. Fast Attack/Slow Release Circuit

LATCHED OUTPUT

The contents of the Bounce Eliminator can be latched by using several extra gates as shown in Figure 7. If the latch lead is high the clock will be stopped when the output goes low. This will hold the output low even though the input has returned to the high state. Any time the clock is stopped the outputs will be representative of the input signal four clock periods earlier.

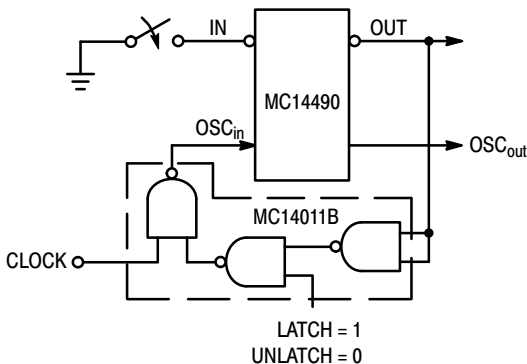


Figure 7. Latched Output Circuit

MULTIPLE TIMING SIGNALS

As shown in Figure 8, the Bounce Eliminator circuits can be connected in series. In this configuration each output is delayed by four clock periods relative to its respective input. This configuration may be used to generate multiple timing signals such as a delay line, for programming other timing operations.

One application of the above is shown in Figure 9, where it is required to have a single pulse output for a single operation (make) of the push button or relay contact. This only requires the series connection of two Bounce Eliminator circuits, one inverter, and one NOR gate in order to generate the signal $\overline{A}B$ as shown in Figures 9 and 10. The signal $\overline{A}B$ is four clock periods in length. If the inverter is switched to the A output, the pulse $\overline{A}B$ will be generated upon release or break of the contact. With the use of a few additional parts many different pulses and waveshapes may be generated.

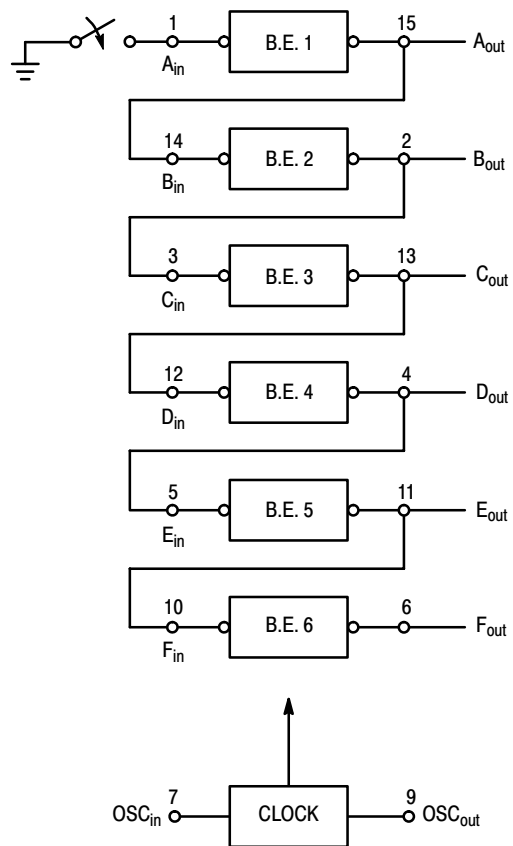


Figure 8. Multiple Timing Circuit Connections

MC14490

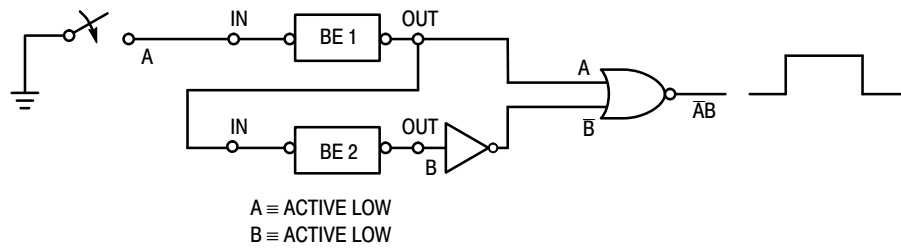


Figure 9. Single Pulse Output Circuit

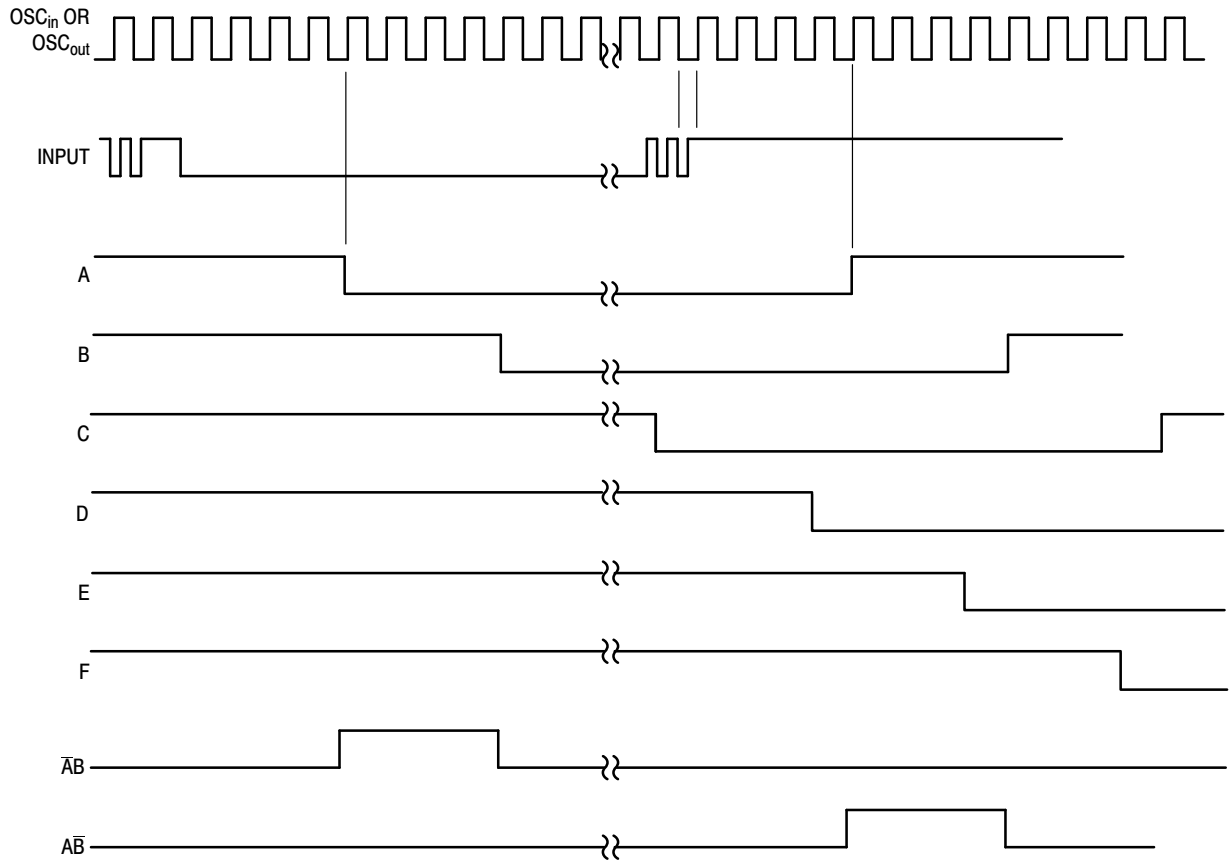


Figure 10. Multiple Output Signal Timing Diagram

MC14490

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14490DWG	SOIC-16 (Pb-Free)	47 Units / Rail
MC14490DWR2G	SOIC-16 (Pb-Free)	1000 / Tape & Reel
NLV14490DWR2G*		

DISCONTINUED (Note 5)

NLV14490DWG*	SOIC-16 (Pb-Free)	47 Units / Rail
MC14490FG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC14490FELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel
MC14490PG	PDIP-16 (Pb-Free)	500 Units / Rail
NLV14490PG*		

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

* NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

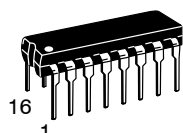
5. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on www.onsemi.com.

MC14490

REVISION HISTORY

Revision	Description of Changes	Date
11	Rebranded the Data Sheet to onsemi format. NLV14490DWG, MC14490FG, MC14490FELG, MC14490PG and NLV14490PG OPNs Marked as Discontinued.	8/27/2025

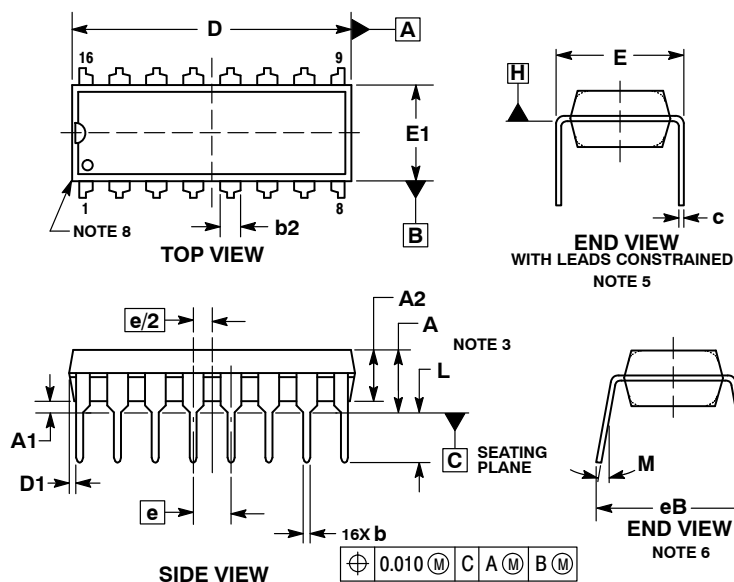
This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.



SCALE 1:1

PDIP-16
CASE 648-08
ISSUE V

DATE 22 APR 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.015	0.210	0.38	5.33
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
C	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005		0.13	
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
eB	0.430			10.92
L	0.115	0.150	2.92	3.81
M	10°		10°	

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:		STYLE 2:	
PIN 1.	CATHODE	PIN 1.	COMMON DRAIN
2.	CATHODE	2.	COMMON DRAIN
3.	CATHODE	3.	COMMON DRAIN
4.	CATHODE	4.	COMMON DRAIN
5.	CATHODE	5.	COMMON DRAIN
6.	CATHODE	6.	COMMON DRAIN
7.	CATHODE	7.	COMMON DRAIN
8.	CATHODE	8.	COMMON DRAIN
9.	ANODE	9.	GATE
10.	ANODE	10.	SOURCE
11.	ANODE	11.	GATE
12.	ANODE	12.	SOURCE
13.	ANODE	13.	GATE
14.	ANODE	14.	SOURCE
15.	ANODE	15.	GATE
16.	ANODE	16.	SOURCE

DOCUMENT NUMBER:	98ASB42431B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PDIP-16	PAGE 1 OF 1

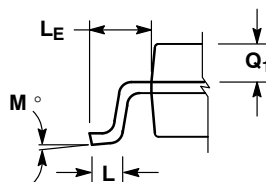
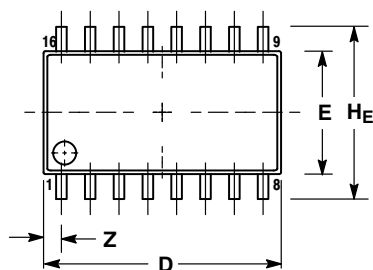
onsemi and **onsemi** are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.



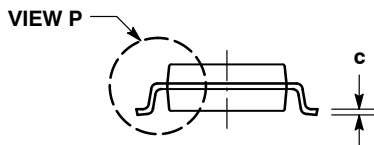
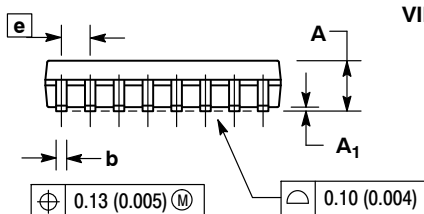
SCALE 1:1

SOEIAJ-16
CASE 966-01
ISSUE A

DATE 27 OCT 2005



DETAIL P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

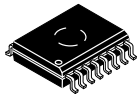
DOCUMENT NUMBER: 98ASH70109A

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: 16 LD SOEIAJ

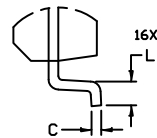
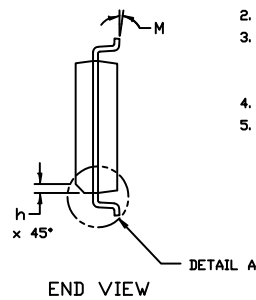
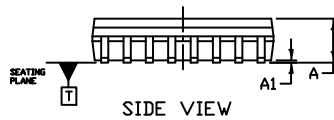
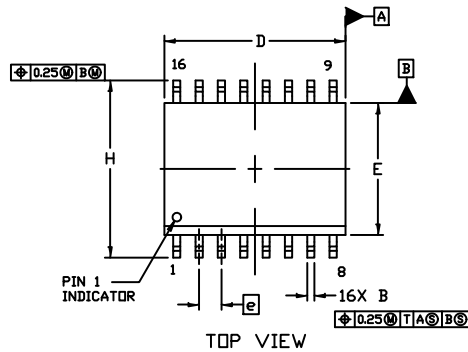
PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.


1
SCALE 1:1

SOIC-16 WB
CASE 751G
ISSUE E

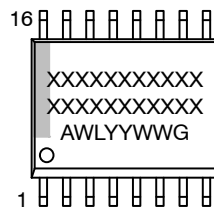
DATE 08 OCT 2021



NOTES:

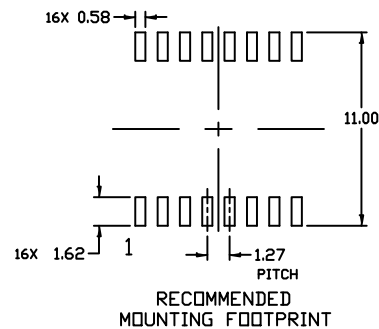
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION OR FLASH TO BE 0.15 PER SIDE.

DIM	MILLIMETERS	
	MIN.	MAX.
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27	BSC
H	10.05	10.55
h	0.53	REF
L	0.50	0.90
M	0°	7°

GENERIC
MARKING DIAGRAM*


XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.


DOCUMENT NUMBER: 98ASB42567B

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: SOIC-16 WB

PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales